

2017 Applied Materials Technical Symposium in China

Inflection Focused Innovation

March 16, 2017, Jumeirah Himalayas Hotel (Morning)

Time		Topic	Speaker
9:00	9:30	Registration	
9:30	9:40	Welcome	Roger Chang, Applied Materials
9:40	10:00	Keynote: Semiconductor Portfolio: Introduction	Erix Yu, Applied Materials
10:00	10:45	Wafer-Level Packaging – The Essential Technology in Enabling the China High Growth Semiconductor Industry	Albert Lan, SPIL
10:45	11:00	Break	
11:00	11:25	Developing Advanced Packaging Equipment Leveraging Applied Packaging Development Center	Arvind Sundarrajan, Applied Materials
11:25	11:50	Metallization Solutions for Advanced Wafer-Level Packaging	Sree Kesapragada, Applied Materials
11:50	12:15	ECD Challenges for Advanced Wafer-Level Packaging	Marvin Bernt, Applied Materials
12:15	13:15	Lunch	

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March 16, 2017, Jumeirah Himalayas Hotel (Afternoon)

Time		Topic	Speaker
13:15	13:45	14nm Technology Development Challenges & Status in SMIC	Beichao Zhang, SMIC
13:45	14:10	Gaining a Competitive Edge with eBeam Metrology and Inspection	Ron Nadler, Applied Materials
14:10	14:35	Reflexion [®] LK Prime [™] for BEOL Applications	Fiona Heung, Applied Materials
14:35	15:00	Centris [®] Sym3 [™] : Symmetric Etch Reactor for Delivering Tunable Local and Cross Wafer Uniformity	Jeffrey Tzong, Applied Materials
15:00	15:15	Break	
15:15	15:40	VIISta [®] Trident [™] High Current – Advanced Ion Implantation Solution for 28nm Technology Node	Qing Zhai, Applied Materials
15:40	16:05	Precision [®] CVD: Next Generation CVD Chamber	David Chu, Applied Materials
16:05	16:30	Data Analytics to Improve Process Tool Performance	Daniel Chou, Applied Materials
16:30	17:30	Closing Reception	